

**POLISHING PAD AND METHOD OF FABRICATING SEMICONDUCTOR
DEVICE USING THE SAME**

ABSTRACT OF THE DISCLOSURE

5 The present disclosure relates to an endpoint detection window of a polishing pad
for use in a polishing process. The polishing pad may prevent an error in detection of the
endpoint of the polishing process by preventing a difference in endpoint detection
performance from occurring due to a difference in the wavelength of a laser between
polishing apparatuses. The present disclosure may also provide a method of fabricating a
10 semiconductor device using the polishing pad.

FIG. 1